Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A circuit device comprising: conductive patterns separated by a separation groove; circuit elements, affixed onto the conductive patterns; and an insulating resin, covering the circuit elements and the conductive patterns and filling the separation groove ~~grooves~~ while exposing the rear surfaces of the conductive patterns;

wherein a protrusion is formed continuously at every side surface of the conductive patterns ~~constricted part is formed at side surface of the separation groove~~ and the insulating resin is adhered to every protrusion ~~the constricted part~~.

2. (Original) The device of Claim 1, wherein the thickness of the conductive patterns is made thicker than the width of the separation groove.

3. (Canceled)

4. (Original) The device of Claim 1, wherein the rear surface and part of the side surface of the conductive patterns are exposed from the insulating resin.

5. (Canceled)

6. (Currently Amended) A circuit device comprising: conductive patterns separated

by a separation groove; a circuit element, affixed onto the conductive pattern; and an insulating resin, covering the circuit element and the conductive patterns and filling the separation groove while exposing the rear surfaces of the conductive patterns;

wherein an etched protrusion is formed continuously at every side surface of the conductive patterns and the insulating resin is adhered to every protrusion. ~~the separation groove is formed of a plurality of grooves formed by etching a plurality of times.~~

7. (Original) The device of Claim 6, wherein the thickness of the conductive patterns is made thicker than the width of the separation groove.

8. (Original) The device of Claim 6, wherein the rear surface and part of the side surface of the conductive patterns are exposed from the insulating resin.

9. (Canceled)

10. (Withdrawn) A circuit device manufacturing method comprising: forming conductive patterns by forming separation grooves at locations of a conductive foil except locations that are to be the conductive patterns; positioning circuit element on the conductive pattern; and forming an insulating resin so as to cover the circuit element and fill the separation groove;

wherein constricted part is formed on side surfaces of the separation grooves by a plurality of times of etching and the insulating resin is adhered to the constricted part.

11. (Withdrawn) The method of Claim 10, wherein

the separation groove is formed by forming a first resist on the surface of the conductive foil so as to cover regions to be the conductive patterns and then performing etching,

and the separation groove is formed deeply to form the constricted part by exposing the

bottom part of the separation grooves, forming a second resist on the surface of the conductive foil, and performing etching again.

12. (Withdrawn) The method of Claim 11, wherein the same mask as the mask used for exposure of the first resist is used for exposure of the second resist to make the second resist remain on side surface of the separation groove.

13. (Withdrawn) The method of Claim 11, wherein the opening width of the second resist is made narrower than the opening width of the first resist to make the second resist remain on side surface of the separation grooves.

14. (Withdrawn) The method of Claim 10, wherein

the separation groove is formed by forming a first resist on the surface of the conductive foil so as to cover regions to be the conductive patterns and then performing etching,

and after covering side surface of the separation groove by the first resist softened by heating, etching is performed again.

15. (Withdrawn) The method of Claim 11, wherein the second resist is formed by vacuum lamination.

16. (Withdrawn) The method of Claim 10, wherein the rear surface of the conductive foil is removed until the insulating resin filling the separation groove becomes exposed.

17. (Withdrawn) The method of Claim 10, wherein the rear surface of the conductive foil is removed selectively at locations at which the separation groove is provided until the insulating resin filling the separation groove becomes exposed.

18. (New) The device of claim 1 wherein side surfaces of the conductive patterns are formed to a curved form.

19. (New) The device of claim 6 wherein side surfaces of the conductive pattern are formed to a curved form.

20. (New) The device of claim 1 wherein a depth of the separation groove is more than twice the width of the separation groove.

21. (New) The device of claim 6 wherein a depth of the separation groove is more than twice the width of the separation groove.

22. (New) The device of claim 1 wherein the conductive patterns protrude outside the insulating resin.

23. (New) The device of claim 6 wherein the conductive patters protrude outside the insulating resin.